
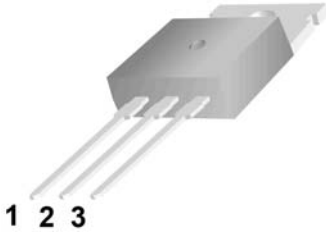
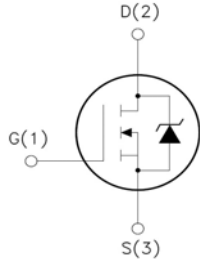


<h3 style="margin: 0;">Features</h3> <ul style="list-style-type: none"> <input type="checkbox"/> Low Intrinsic Capacitances <input type="checkbox"/> Excellent Switching Characteristics <input type="checkbox"/> Extended Safe Operating Area <input type="checkbox"/> Unrivalled Gate Charge : 22 nC (Typ.) <input type="checkbox"/> BVDSS=200V, ID=10A <input type="checkbox"/> Lower $R_{DS(on)}$: 0.4 Ω (Max) @VG=10V <input type="checkbox"/> 100% Avalanche Tested 	<div style="display: flex; justify-content: space-between; align-items: center;"> TO-220F  </div> <div style="text-align: center; margin-top: 20px;">  <p>1 2 3</p>  </div> <div style="margin-top: 10px;"> <p>1.Gate (G)</p> <p>2.Drain (D)</p> <p>3.Source (S)</p> </div>
--	---

Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	200	V
I_D	Drain Current	$T_j=25^\circ\text{C}$	10.0
		$T_j=100^\circ\text{C}$	7.0
$V_{GS(TH)}$	Gate Threshold Voltage	± 30	V
E_{AS}	Single Pulse Avalanche Energy (note1)	160	mJ
I_{AR}	Avalanche Current (note2)	9.0	A
P_D	Power Dissipation ($T_j=25^\circ\text{C}$)	140	W
T_j	Junction Temperature(Max)	150	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~+150	$^\circ\text{C}$
TL	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case	-	0.88	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	62.5	$^\circ\text{C}/\text{W}$

Symbol	Parameter	Test Condition	Min.	Typ.	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\ \mu A, V_{GS}=0$	200	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D=250\ \mu A$, Reference to 25°C	--	0.55	--	V/°C
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=200V, V_{GS}=0V$	--	--	1	μA
		$V_{DS}=160V, T_C=125^\circ C$			10	μA
I_{GSSF}	Gate-body leakage Current, Forward	$V_{GS}=+30V, V_{DS}=0V$	--	--	100	nA
I_{GSSR}	Gate-body leakage Current, Reverse	$V_{GS}=-30V, V_{DS}=0V$	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$I_D=250\ \mu A, V_{DS}=V_{GS}$	2	--	4	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$I_D=10A, V_{GS}=10V$	--	--	0.4	Ω
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0, f=1.0MHz$	--	710	-	pF
C_{oss}	Output Capacitance		--	85	-	pF
C_{rss}	Reverse Transfer Capacitance		--	22	-	pF
Switching Characteristics						
$T_d(on)$	Turn-On Delay Time	$V_{DD}=100V, I_D=10A, R_G=25\ \Omega$ (Note 3,4)	--	11	25	nS
T_r	Turn-On Rise Time		--	70	140	nS
$T_d(off)$	Turn-Off Delay Time		--	60	120	nS
T_f	Turn-Off Fall Time		--	65	130	nS
Q_g	Total Gate Charge	$V_{DS}=160, V_{GS}=10V, I_D=10A$ (Note 3,4)	--	22	30	nC
Q_{gs}	Gate-Source Charge		--	4	--	nC
Q_{gd}	Gate-Drain Charge		--	11	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current		--	--	10	A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	40	A
V_{SD}	Drain-Source Diode Forward Voltage	$I_D=10A$	--	--	1.45	V
t_{rr}	Reverse Recovery Time	$I_S=10A, V_{GS}=0V, di_F/dt=100A/\mu S$ (Note3)	--	140	--	nS
Q_{rr}	Reverse Recovery Charge		--	2.2	--	μC
*Notes 1, $L=8mH, I_{AS}=10A, V_{DD}=50V, R_G=25\Omega$, Starting $T_J=25^\circ C$ 2, Repetitive Rating : Pulse width limited by maximum junction temperature 3, Pulse Test : Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$ 4, Essentially Independent of Operating Temperature						

Typical Characteristics

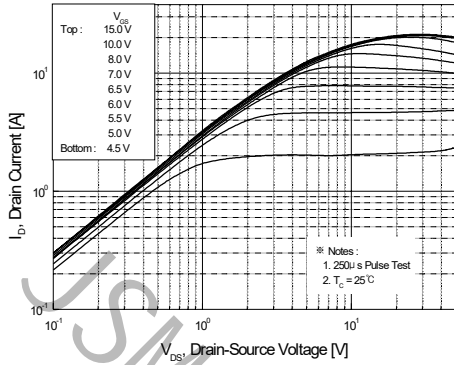


Figure 1. On-Region Characteristics

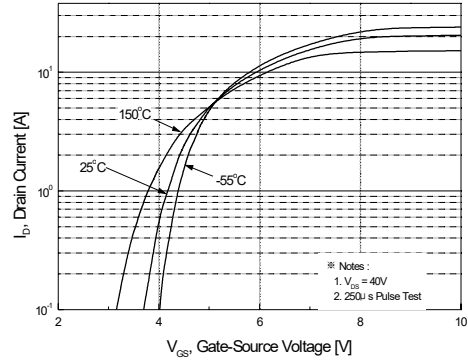


Figure 2. Transfer Characteristics

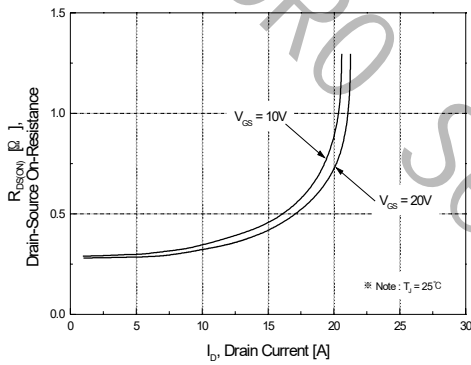


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

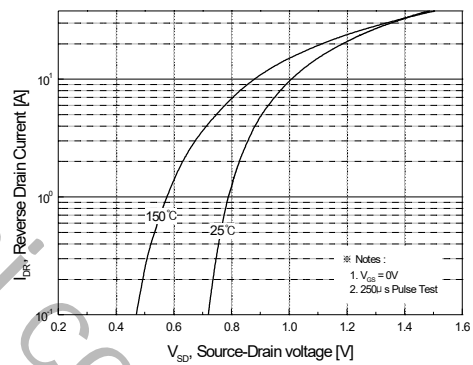


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

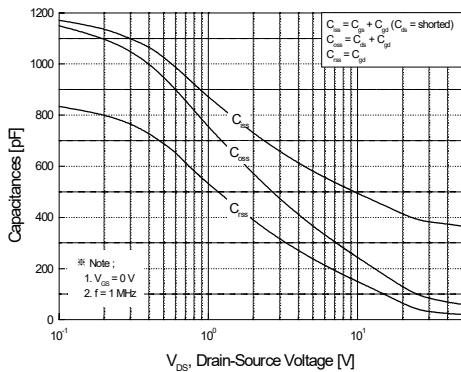


Figure 5. Capacitance Characteristics

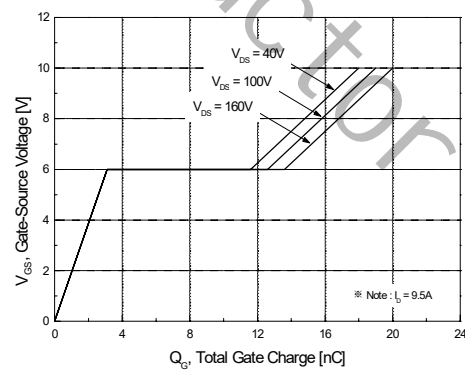


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

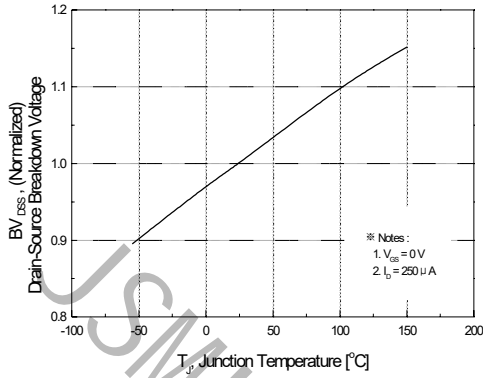


Figure 7. Breakdown Voltage Variation vs Temperature

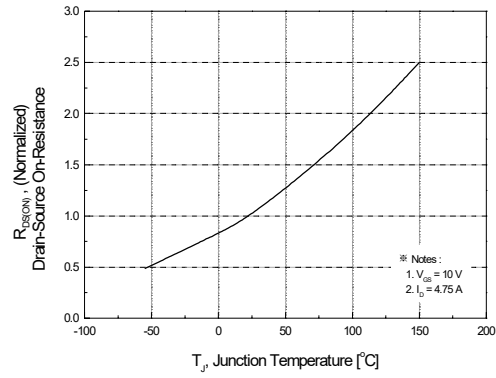


Figure 8. On-Resistance Variation vs Temperature

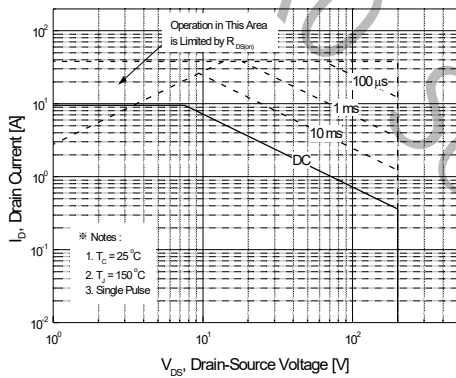


Figure 9-1. Maximum Safe Operating Area

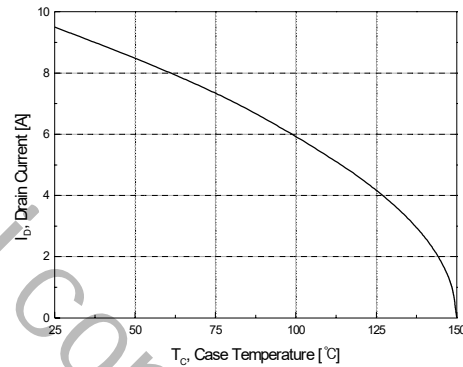


Figure 10. Maximum Drain Current vs Case Temperature

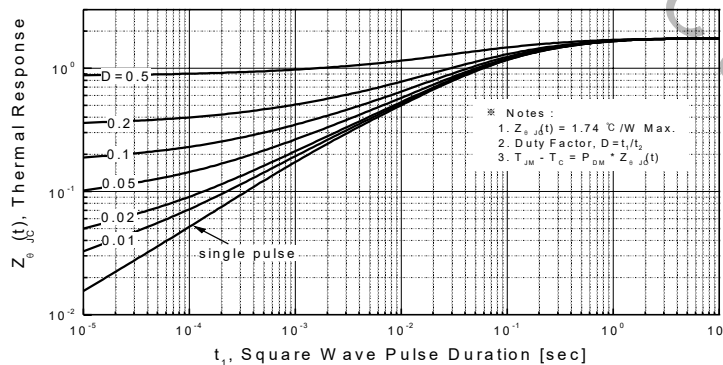
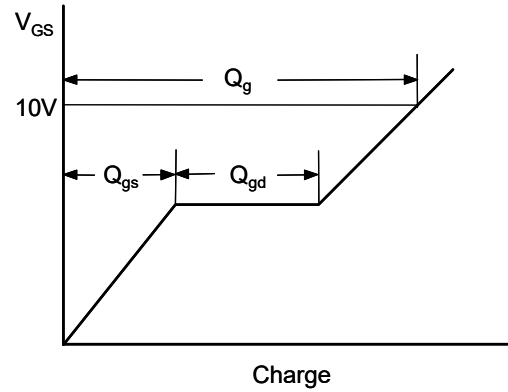
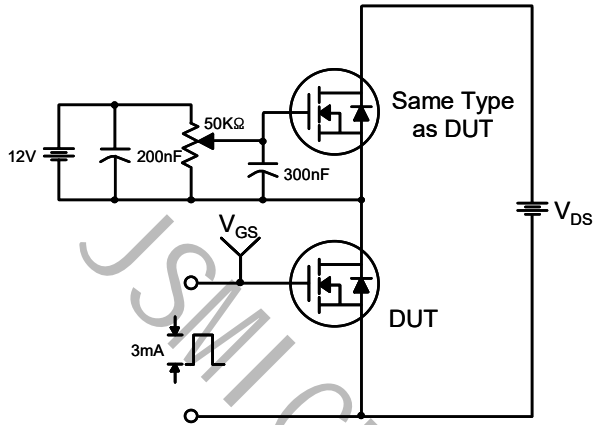
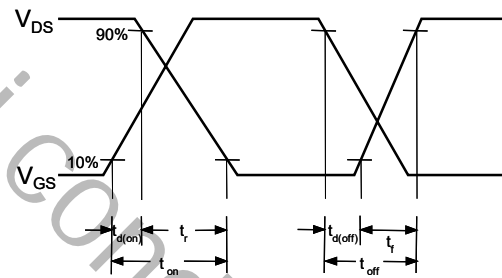
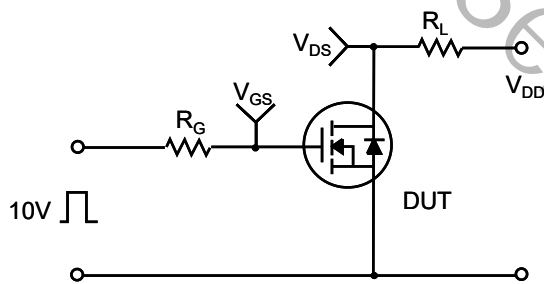
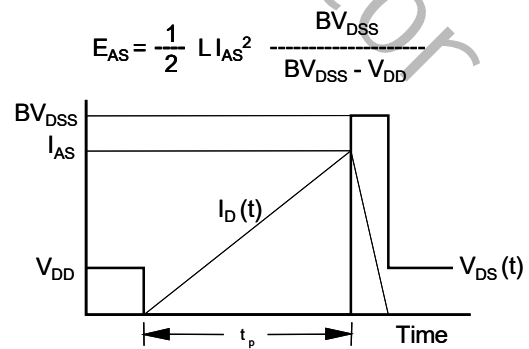
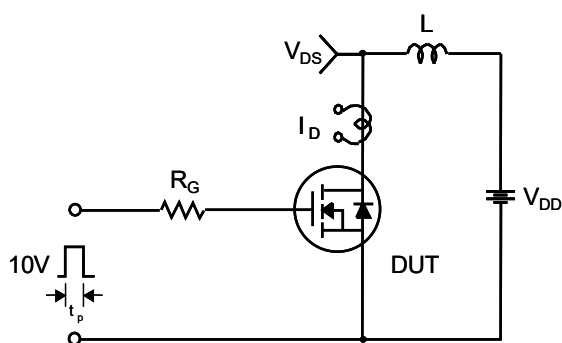
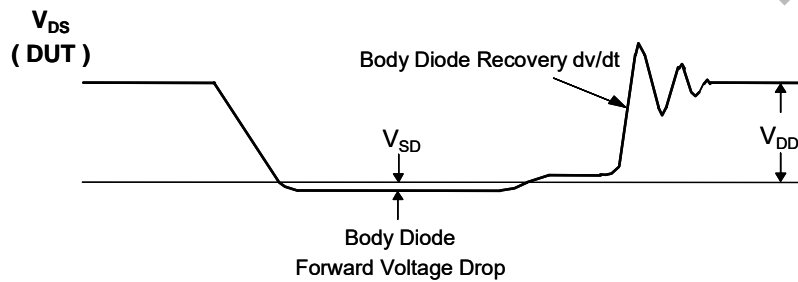
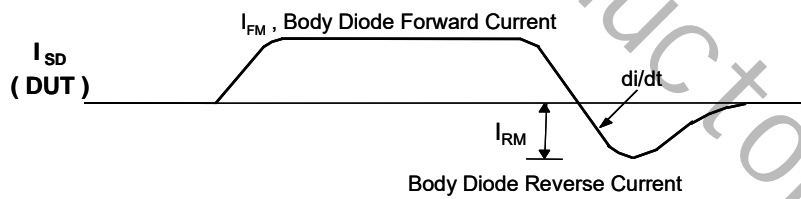
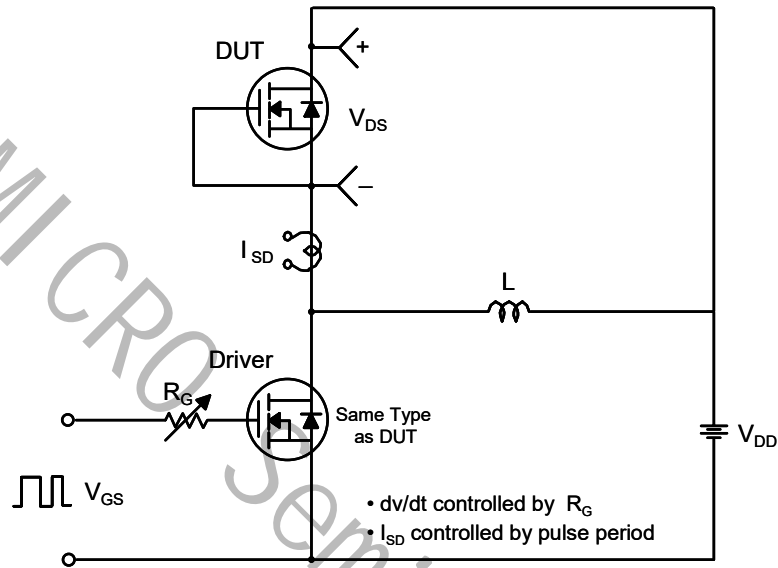


Figure 11-1. Transient Thermal Response Curve

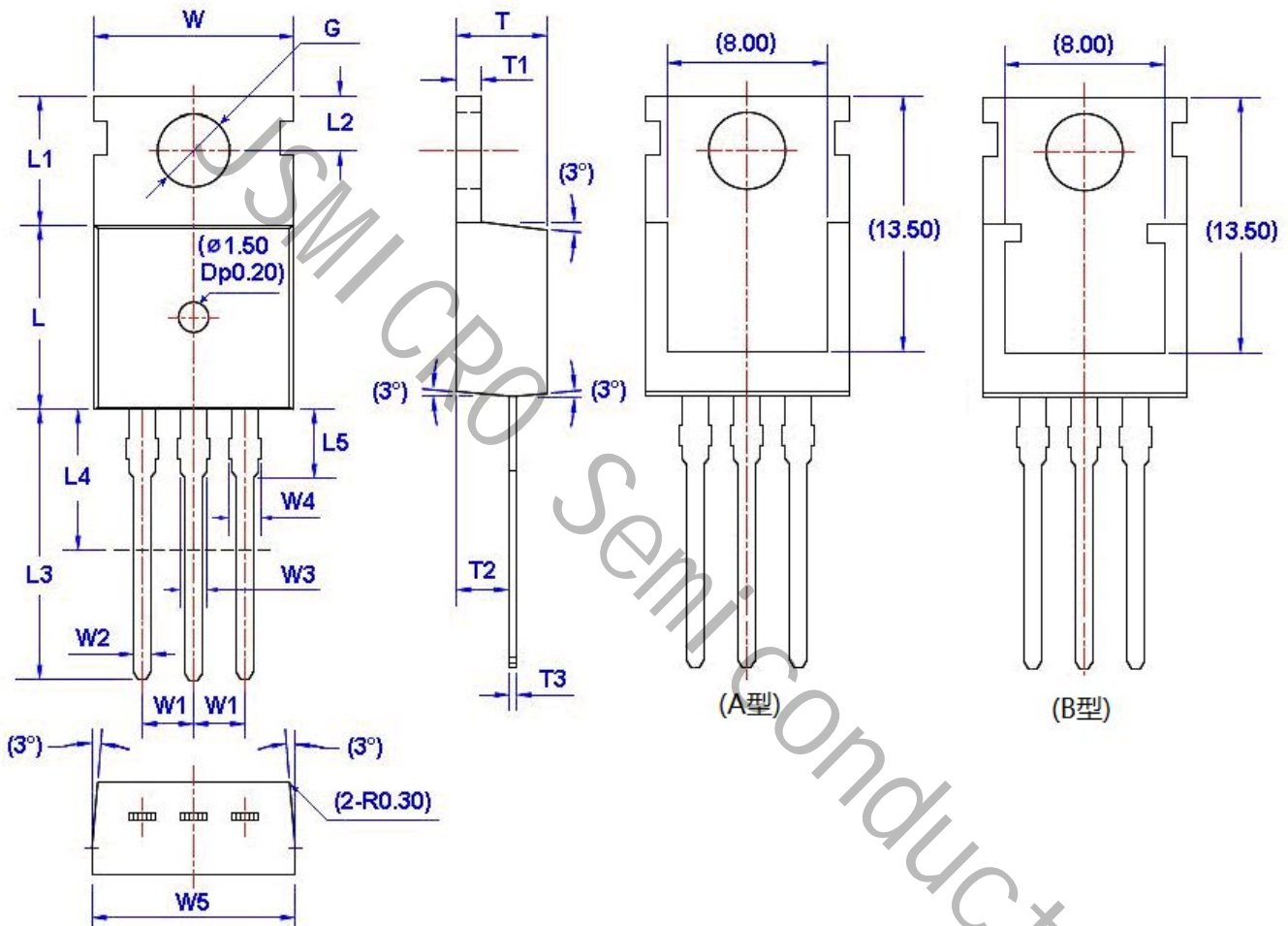
Gate Charge Test Circuit & Waveform

Resistive Switching Test Circuit & Waveforms

Unclamped Inductive Switching Test Circuit & Waveforms


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Package Dimension
TO-220

Unit:mm



Symbol	Size		Symbol	Size		Symbol	Size		Symbol	Size	
	Min	Max		Min	Max		Min	Max		Min	Max
W	9.66	10.28	W5	9.80	10.20	L4**	6.20	6.60	T3	0.45	0.60
W1	2.54 (TYP)		L	9.00	9.40	L5	2.79	3.30	G(Φ)	3.50	3.70
W2	0.70	0.95	L1	6.40	6.80	T	4.30	4.70			
W3	1.17	1.37	L2	2.70	2.90	T1	1.15	1.40			
W4*	1.32	1.72	L3	12.70	14.27	T2	2.20	2.60			